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AMENDMENT

CLAIMS

1. (Amended) A heat-treated resin molding obtained by heat-treating a specific portion of a resin molding (W) partially at a high temperature which specific portion is apt to undergo peeling of a thin surface resin film of the resin molding (W), the resin molding (W) being produced by molding with use of a mold and to be subjected to plating with resin.
2. (Deleted)
3. (Amended) A heat-treated resin molding according to claim 1, wherein a parting line portion (W1) of the resin molding (W) is heat-treated at a high temperature.
4. (Deleted)
5. (Amended) A heat-treated resin molding according to any of claim 1 or claim 3, wherein the resin molding (W) is heat-treated at a high temperature so that rubber particles in the resin surface of the resin molding retain a generally circular shape.
6. (Amended) A heat-treated resin molding according to any of claims 1, 3 and 5, wherein the resin molding (W) is heat-treated so that rubber particles in the resin surface of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse

directions.

7. (Amended) A heat-treated resin molding according to any of claim 1 or 3, wherein the resin molding (W) to be partially heat-treated at a high temperature is a resin molding produced by molding in an injection molding machine.

8. A resin molding heat-treating apparatus (1) for heat-treating a parting line portion (W1) of a resin molding (W) or a specific portion of the resin molding (W), which portion is apt to undergo peeling of a thin surface resin film, partially at a high temperature,

the apparatus (1) comprising:

heating section (2) having a shape conforming to a contour line of a portion to be heated of the resin molding (W); and

a fixing jig (4) for fixing the resin molding (W) removably,

wherein the portion to be heated of the resin molding (W) is heat-treated at a high temperature while being approximated to the heating section (2).

9. A resin molding heat-treating apparatus according to claim 8, wherein the fixing jig (4) is attached to several positions of a rotary disc (3) and the portion to be heated of the resin molding (W) projects from the peripheral edge of the rotary disc (3) so as to pass through a heat-

treating space (S) formed in the heating section (2).

10. A resin molding heat-treating apparatus according to claim 8 or claim 9, wherein a shield plate (8) having an opening portion (7) of a shape conforming to the contour line of the portion to be heated of the resin molding (W) is disposed in a sandwiching relation to the heating section (2) so that the other portion than the portion to be heated of the resin molding (W) is not heated.

11. A resin molding heat-treating apparatus according to claim 8, wherein the fixing jig (4) is attached to several positions of a side edge of a belt member and the portion to be heated of the resin molding (W) projects from the belt member so as to pass through a heat-treating space (S) formed in the heating section (2).

12. A resin molding heat-treating apparatus according to claim 8, wherein the heating section (2) is constructed such that a large number of fine holes are formed in a pipe which is analogous to the contour line of the resin molding (W) and which is bent so as to be in a shape about twice as large as the resin molding (W), and hot air is ejected through the fine holes to heat the resin molding.

13. A resin molding heat-treating apparatus according to claim 8, wherein the heating section (2) is constructed such that a member analogous to the contour line of the

resin molding (W) and having a shape about twice as large as the resin molding (W) is heated by an electromagnetic induction heating method.

14. A resin molding heat-treating apparatus according to claim 8, wherein the heating section (2) is constructed such that a member analogous to the contour line of the resin molding (W) and having a shape about twice as large as the resin molding (W) is heated by a high-frequency heating method.